12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20250709002.1
Qualification of RFAB as an additional Fab site option,
Die Revision, Datasheet & Device marking change for select devices
Change Notification / Sample Request

Date: July 10, 2025
To: Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20250709002.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74LVC1G14DBVR	NULL
SN74LVC1G07DBVR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250709002.1	PCN Date:	July 10, 2025
Title:	Qualification of RFAB as an additional Fab site option, Die Revision, Datasheet, & BOM options for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	October 08, 2025	Sample requests accepted until:	September 08, 2025*

*Sample requests received after September 08, 2025 will not be supported.

Change Type:

☐	Assembly Site	☒	Design	☐	Wafer Bump Material
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Process
☐	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☒	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of RFAB as an additional Fab site option & Device marking change for the devices listed below.

Current Fab Site			Additional Fab site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab site**	**Process**	**Wafer Diameter**
FFAB	ASLC10	200mm	RFAB	LBC9PLV	300mm

The die was also changed as a result of the process change.

Marking differences are as follows:

Device name	Current Symbol	New Symbol
SN74LVC1G04DBVR, SN74LVC1G04DBVR.A, SN74LVC1G04DBVR.B	C04J, C04K, C04R, C04H, C04P, C04S	**3VHF**
SN74LVC1G06DBVR SN74LVC1G06DBVR.A SN74LVC1G06DBVR.B	C065, C06F, C06J, C06R, C06T, C06H, C06P, C06S	**3VSF**
SN74LVC1G07DBVR SN74LVC1G07DBVR.A SN74LVC1G07DBVR.B	C075, C07F, C07J, C07K, C07R, C07T, C07H, C07P, C07S	**3VTF**
SN74LVC1G14DBVR SN74LVC1G14DBVR.A SN74LVC1G14DBVR.B	C145, C14F, C14J, C14K, C14R, C14H, C14S	**3VUF**
SN74LVC1G17DBVR SN74LVC1G17DBVR.A SN74LVC1G17DBVR.B	C175, C17F, C17J, C17K, C17R C17H, C17P, C17S	**3VVF**
SN74LVC1G34DBVR SN74LVC1G34DBVR.A SN74LVC1G34DBVR.B	C345, C34F, C34J, C34K, C34R, C34H, C34P, C34S	**3VWF**

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.

TEXAS INSTRUMENTS

SN74LVC1G17

SCES351X – JULY 2001 – REVISED JUNE 2025

Changes from Revision W (September 2020) to Revision X (June 2025) **Page**

- Updated the document to reflect TI writing standards..... 1
- Changed *Device Information* table to *Package Information* 1
- Moved T_{stg} to *Absolute Maximum Ratings* table..... 4
- Changed *Handling Ratings* to *ESD Ratings* 4
- Changed Junction-to-ambient thermal resistance value for DBV package from: 229°C/W to: 357.1°C/W 5
- Changed Junction-to-case (top) thermal resistance value for DBV package from: 164°C/W to: 263.7°C/W..... 5
- Changed Junction-to-board thermal resistance value for DBV package from: 62°C/W to: 264.4°C/W..... 5
- Changed Junction-to-top characterization value for DBV package from: 44°C/W to: 195.6°C/W..... 5
- Changed Junction-to-board characterization value for DBV package from: 62°C/W to: 262.2°C/W..... 5
- Removed rise time and fall time information from the recommended input conditions in the *Detailed Design Procedure* 11

TEXAS INSTRUMENTS

SN74LVC1G04

SCES214AE – APRIL 1999 – REVISED JUNE 2025

Changes from Revision AD (April 2014) to Revision AE (June 2025) **Page**

- Updated the numbering format for tables, figures, and cross-references throughout the document..... 1
- Changed *Device Information* table to *Package Information* 1
- Moved T_{stg} to *Absolute Maximum Ratings* table..... 4
- Changed Handling Ratings to ESD Ratings..... 4
- Changed Junction-to-ambient thermal resistance value for DBV package from: 229°C/W to: 357.1°C/W 5
- Changed Junction-to-case (top) thermal resistance value for DBV package from: 164°C/W to: 263.7°C/W 5
- Changed Junction-to-board thermal resistance value for DBV package from: 62°C/W to: 264.4°C/W 5
- Changed Junction-to-top characterization value for DBV package from: 44°C/W to: 195.6°C/W 5
- Changed Junction-to-board characterization value for DBV package from: 62°C/W to: 262.2°C/W 5

TEXAS INSTRUMENTS

SN74LVC1G14

SCES218Z – APRIL 1999 – REVISED JUNE 2025

Changes from Revision Y (November 2018) to Revision Z (June 2025) **Page**

- Updated the numbering format for tables, figures, and cross-references throughout the document..... 1
- Changed *Device Information* table to *Package Information* 1
- Changed Junction-to-ambient thermal resistance value for DBV package from: 247.2°C/W to: 357.1°C/W 6
- Changed Junction-to-case (top) thermal resistance value for DBV package from: 154.5°C/W to: 263.7°C/W..... 6
- Changed Junction-to-board thermal resistance value for DBV package from: 86.8°C/W to: 264.4°C/W..... 6
- Changed Junction-to-top characterization value for DBV package from: 58.0°C/W to: 195.6°C/W..... 6
- Changed Junction-to-board characterization value for DBV package from: 86.4°C/W to: 262.2°C/W..... 6

TEXAS INSTRUMENTS

SN74LVC1G06

SCES295AA – JUNE 2000 – REVISED JUNE 2025

Changes from Revision Z (November 2017) to Revision AA (June 2025) **Page**

- Updated the numbering format for tables, figures, and cross-references throughout the document..... 1
- Changed *Device Information* table to *Package Information* 1
- Changed Junction-to-ambient thermal resistance value for DBV package from: 231.5°C/W to: 357.1°C/W 5
- Changed Junction-to-case (top) thermal resistance value for DBV package from: 139.4°C/W to: 263.7°C/W 5
- Changed Junction-to-board thermal resistance value for DBV package from: 71.1°C/W to: 264.4°C/W 5
- Changed Junction-to-top characterization value for DBV package from: 45.2°C/W to: 195.6°C/W 5
- Changed Junction-to-board characterization value for DBV package from: 70.7°C/W to: 262.2°C/W 5

TEXAS INSTRUMENTS

SN74LVC1G07

SCES296AF – FEBRUARY 2000 – REVISED JUNE 2025

Changes from Revision AE (September 2020) to Revision AF (June 2025) **Page**

- Changed *Device Information* table to *Package Information* 1
- Changed Junction-to-ambient thermal resistance value for DBV package from: 229°C/W to: 357.1°C/W 5
- Changed Junction-to-case (top) thermal resistance value for DBV package from: 164°C/W to: 263.7°C/W 5
- Changed Junction-to-board thermal resistance value for DBV package from: 62°C/W to: 264.4°C/W 5
- Changed Junction-to-top characterization value for DBV package from: 44°C/W to: 195.6°C/W..... 5
- Changed Junction-to-board characterization value for DBV package from: 62°C/W to: 262.2°C/W..... 5

Changes from Revision M (April 2016) to Revision N (June 2025) **Page**

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
SN74LVC1G17	SCES351W	**SCES351X**	http://www.ti.com/product/SN74LVC1G17
SN74LVC1G04	SCES214AD	**SCES214AE**	http://www.ti.com/product/SN74LVC1G04
SN74LVC1G14	SCES218Y	**SCES218Z**	http://www.ti.com/product/SN74LVC1G14
SN74LVC1G06	SCES295Z	**SCES295AA**	http://www.ti.com/product/SN74LVC1G06
SN74LVC1G07	SCES296AE	**SCES296AF**	http://www.ti.com/product/SN74LVC1G07
SN74LVC1G34	SCES519M	**SCES519N**	http://www.ti.com/product/SN74LVC1G34

Qual details are provided in the Qual Data Section.
Test coverage, insertions, conditions will remain consistent with current testing.

Reason for Change:

Supply Continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
FFAB	TID	DEU	Freising
RFAB	**RFB**	**USA**	**Richardson**

Die Rev:

Current	New
Die Rev [2P]	**Die Rev [2P]**
D, G	**A**

Sample product shipping label (not actual product label):

Product Affected:

SN74LVC1G04DBVR	SN74LVC1G07DBVR	SN74LVC1G17DBVR
SN74LVC1G04DBVR.A	SN74LVC1G07DBVR.A	SN74LVC1G17DBVR.A
SN74LVC1G04DBVR.B	SN74LVC1G07DBVR.B	SN74LVC1G17DBVR.B
SN74LVC1G06DBVR	SN74LVC1G14DBVR	SN74LVC1G34DBVR
SN74LVC1G06DBVR.A	SN74LVC1G14DBVR.A	SN74LVC1G34DBVR.A
SN74LVC1G06DBVR.B	SN74LVC1G14DBVR.B	SN74LVC1G34DBVR.B

CDAT Qualification Report

Approve Date 19-JUNE -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74LVC1G04DBVR	**Qual Device: SN74LVC1G06DBVR**	QBS Reference: SN74HCS74QPWRQ1	**QBS Reference: TPS3840PH30DBVRQ1**	QBS Reference: SN74AHC1G00DBVRQ1	**QBS Reference: CAHCT1G14QDBVRQ1**	QBS Reference: CAHCT1G32QDBVRQ1	**QBS Reference: SN74LVC1G16DBVR**
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0	1/77/0	1/77/0	1/77/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	-	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	1/77/0	1/77/0	1/77/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	3/231/0	1/77/0	1/77/0	1/77/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	3/135/0	-	-	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	-	1/45/0	1/45/0	1/45/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	3/231/0	-	-	-	1/77/0
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	1/77/0	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	-	-	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	1/15/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	1/15/0	-	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	3/30/0	1/10/0	1/10/0	1/10/0	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	-	-	-	-	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	-	1/3/0	-	1/3/0	-	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	-	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	1/6/0	-	-	-	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	-	-	-	-	-	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0	3/90/0	1/30/0	1/30/0	1/30/0	-

QBS: Qual By Similarity, also known as Generic Data
Qual Device SN74LVC1G04DBVR is qualified at MSL1 260C
Qual Device SN74LVC1G06DBVR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2411-051

TIPI Qualification Report

Approve Date 19-JUNE -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74LVC1G04DBVR	**Qual Device: SN74LVC1G06DBVR**	QBS Reference: TLV1805QDBVRQ1	**QBS Reference: SN74HCS74QPWRQ1**	QBS Reference: TLV1805QDBVRQ1	**QBS Reference: SN74LVC1G16DBVR**
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	3/135/0	3/135/0	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	3/135/0	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	3/231/0	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	-	1/77/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	3/2400/0	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	1/15/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	1/15/0	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	3/30/0	3/30/0	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	-	-	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	-	1/3/0	1/3/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	1/6/0	1/6/0	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	-	-	-	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0	3/90/0	3/90/0	-

QBS: Qual By Similarity, also known as Generic Data
Qual Device SN74LVC1G04DBVR is qualified at MSL1 260C
Qual Device SN74LVC1G06DBVR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2411-053

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.